

# Table of Contents

<b>1 General</b> .....	1-1	<b>1.11 Acceptance Requirements</b> .....	1-7
<b>1.1 Scope</b> .....	1-2	<b>1.12 Inspection Methodology</b> .....	1-7
<b>1.2 Purpose</b> .....	1-3	1.12.1 Lighting .....	1-7
<b>1.3 Classification</b> .....	1-3	1.12.2 Magnification Aids .....	1-7
<b>1.4 Measurement Units and Applications</b> .....	1-3	<b>2 Applicable Documents</b> .....	2-1
1.4.1 Verification of Dimensions .....	1-3	<b>2.1 IPC Documents</b> .....	2-1
<b>1.5 Definition of Requirements</b> .....	1-3	<b>2.2 Joint Industry Documents</b> .....	2-1
1.5.1 Acceptance Criteria .....	1-4	<b>2.3 Electrostatic Association Documents</b> .....	2-2
1.5.1.1 Target Condition .....	1-4	<b>2.4 JEDEC</b> .....	2-2
1.5.1.2 Acceptable Condition .....	1-4	<b>2.5 International Electrotechnical Commission Documents</b> .....	2-2
1.5.1.3 Defect Condition .....	1-4	<b>2.6 ASTM</b> .....	2-2
1.5.1.3.1 Disposition .....	1-4	<b>2.7 Military Standards</b> .....	2-2
1.5.1.4 Process Indicator Condition .....	1-4	<b>3 Handling Electronic Assemblies</b> .....	3-1
1.5.1.5 Combined Conditions .....	1-4	<b>3.1 EOS/ESD Prevention</b> .....	3-2
1.5.1.6 Conditions Not Specified .....	1-4	3.1.1 Electrical Overstress (EOS) .....	3-3
1.5.1.7 Specialized Designs .....	1-5	3.1.2 Electrostatic Discharge (ESD) .....	3-4
<b>1.6 Process Control Methodologies</b> .....	1-5	3.1.3 Warning Labels .....	3-5
<b>1.7 Order of Precedence</b> .....	1-5	3.1.4 Protective Materials .....	3-6
1.7.1 Clause References .....	1-5	<b>3.2 EOS/ESD Safe Workstation/EPA</b> .....	3-7
1.7.2 Appendices .....	1-5	<b>3.3 Handling Considerations</b> .....	3-9
<b>1.8 Terms and Definitions</b> .....	1-5	3.3.1 Guidelines .....	3-9
1.8.1 Board Orientation .....	1-5	3.3.2 Physical Damage .....	3-10
1.8.1.1 *Primary Side .....	1-5	3.3.3 Contamination .....	3-10
1.8.1.2 *Secondary Side .....	1-5	3.3.4 Electronic Assemblies .....	3-11
1.8.1.3 Solder Source Side .....	1-5	3.3.5 After Soldering .....	3-11
1.8.1.4 Solder Destination Side .....	1-5	3.3.6 Gloves and Finger Cots .....	3-12
1.8.2 *Cold Solder Connection .....	1-6	<b>4 Hardware</b> .....	4-1
1.8.3 Diameter .....	1-6	<b>4.1 Hardware Installation</b> .....	4-2
1.8.4 Electrical Clearance .....	1-6	4.1.1 Electrical Clearance .....	4-2
1.8.5 FOD (Foreign Object Debris) .....	1-6	4.1.2 Interference .....	4-3
1.8.6 High Voltage .....	1-6	4.1.3 Component Mounting – High Power .....	4-4
1.8.7 Intrusive Solder .....	1-6	4.1.4 Heatsinks .....	4-6
1.8.8 Locking Mechanism .....	1-6	4.1.4.1 Insulators and Thermal Compounds .....	4-6
1.8.9 Meniscus (Component) .....	1-6	4.1.4.2 Contact .....	4-8
1.8.10 *Nonfunctional Land .....	1-6	4.1.5 Threaded Fasteners and Other Threaded Hardware .....	4-9
1.8.11 Pin-in-Paste .....	1-6	4.1.5.1 Torque .....	4-11
1.8.12 Solder Balls .....	1-6	4.1.5.2 Wires .....	4-13
1.8.13 *Stress Relief .....	1-6		
1.8.14 Wire Overlap .....	1-6		
1.8.15 Wire Overwrap .....	1-6		
<b>1.9 Requirements Flowdown</b> .....	1-6		
<b>1.10 Personnel Proficiency</b> .....	1-7		

# Table of Contents

<b>1 General</b> .....	1-1	1.8.22 Tempered Leads .....	1-6
<b>1.1 Scope</b> .....	1-1	1.8.23 Wire Overlap .....	1-6
<b>1.2 Purpose</b> .....	1-1	1.8.24 Wire Overwrap .....	1-6
<b>1.3 Classification</b> .....	1-2	1.8.25 User .....	1-6
<b>1.4 Measurement Units and Applications</b> .....	1-2	<b>1.9 Requirements Flowdown</b> .....	1-6
1.4.1 Verification of Dimensions .....	1-2	<b>1.10 Personnel Proficiency</b> .....	1-6
<b>1.5 Definition of Requirements</b> .....	1-2	<b>1.11 Acceptance Requirements</b> .....	1-6
1.5.1 Acceptance Criteria .....	1-3	1.11.1 Missing Parts and Components .....	1-6
1.5.1.1 Acceptable Condition .....	1-3	<b>1.12 Inspection Methodology</b> .....	1-6
1.5.1.2 Defect Condition .....	1-3	1.12.1 Lighting .....	1-7
1.5.1.2.1 Disposition .....	1-3	1.12.2 Magnification Aids .....	1-7
1.5.1.3 Process Indicator Condition .....	1-3	<b>2 Applicable Documents</b> .....	2-1
1.5.1.4 Combined Conditions .....	1-3	<b>2.1 IPC Documents</b> .....	2-1
1.5.1.5 Conditions Not Specified .....	1-3	<b>2.2 Joint Industry Documents</b> .....	2-1
1.5.1.6 Specialized Designs .....	1-3	<b>2.3 Electrostatic Association Documents</b> .....	2-2
1.5.1.7 Should .....	1-4	<b>2.4 International Electrotechnical Commission Documents</b> .....	2-2
<b>1.6 Process Control Methodologies</b> .....	1-4	<b>2.5 ASTM</b> .....	2-2
<b>1.7 Order of Precedence</b> .....	1-4	<b>2.6 Military Standards</b> .....	2-2
1.7.1 Clause References .....	1-4	<b>2.7 SAE International</b> .....	2-2
1.7.2 Appendices .....	1-4	<b>3 Handling Electronic Assemblies</b> .....	3-1
<b>1.8 Terms and Definitions</b> .....	1-4	<b>4 Hardware</b> .....	4-1
1.8.1 Board Orientation .....	1-4	<b>4.1 Hardware Installation</b> .....	4-2
1.8.1.1 Primary Side .....	1-4	4.1.1 Electrical Clearance .....	4-2
1.8.1.2 Secondary Side .....	1-4	4.1.2 Interference .....	4-3
1.8.1.3 Solder Source Side .....	1-4	4.1.3 Component Mounting – High Power .....	4-4
1.8.1.4 Solder Destination Side .....	1-4	4.1.4 Heatsinks .....	4-6
1.8.2 Cold Solder Connection .....	1-4	4.1.4.1 Insulators and Thermal Compounds .....	4-6
1.8.3 Common Conductors .....	1-4	4.1.4.2 Contact .....	4-7
1.8.4 Diameter .....	1-5	4.1.5 Threaded Fasteners and Other Threaded Hardware .....	4-8
1.8.5 Electrical Clearance .....	1-5	4.1.5.1 Torque .....	4-10
1.8.6 Engineering Documentation .....	1-5	4.1.5.2 Solid Wires .....	4-12
1.8.7 FOD (Foreign Object Debris) .....	1-5	4.1.5.3 Stranded Wires .....	4-14
1.8.8 Form, Fit, Function (F/F/F) .....	1-5	<b>4.2 Jackpost Mounting</b> .....	4-15
1.8.9 High Voltage .....	1-5	<b>4.3 Connector Pins</b> .....	4-16
1.8.10 Intrusive Solder .....	1-5	4.3.1 Edge Connector Pins .....	4-16
1.8.11 Kink .....	1-5	4.3.2 Press Fit Pins .....	4-16
1.8.12 Locking Mechanism .....	1-5	4.3.2.1 Land/Annular Ring .....	4-18
1.8.13 Manufacturer .....	1-5	4.3.2.2 Soldering .....	4-19
1.8.14 Meniscus (Component) .....	1-5	<b>4.4 Wire Bundle Securing</b> .....	4-20
1.8.15 Noncommon Conductors .....	1-5	<b>4.5 Routing – Wires and Wire Bundles</b> .....	4-20
1.8.16 Nonfunctional Land .....	1-5		
1.8.17 Pin-in-Paste .....	1-5		
1.8.18 Solder Balls .....	1-6		
1.8.19 Standard Industry Practice (SIP) .....	1-6		
1.8.20 Stress Relief .....	1-6		
1.8.21 Supplier .....	1-6		

## Table of Contents (cont.)

<b>4.2 Jackpost Mounting</b> .....	4-15	<b>6.1.2 Rolled Flange</b> .....	6-7
<b>4.3 Connector Pins</b> .....	4-16	<b>6.1.3 Flared Flange</b> .....	6-8
4.3.1 Edge Connector Pins .....	4-16	<b>6.1.4 Controlled Split</b> .....	6-9
4.3.2 Press Fit Pins .....	4-17	<b>6.1.5 Solder</b> .....	6-10
4.3.2.1 Soldering .....	4-20	<b>6.2 Insulation</b> .....	6-12
<b>4.4 Wire Bundle Securing</b> .....	4-23	6.2.1 Damage .....	6-12
4.4.1 General .....	4-23	6.2.1.1 Presolder .....	6-12
4.4.2 Lacing .....	4-26	6.2.1.2 Post-Solder .....	6-14
4.4.2.1 Damage .....	4-27	6.2.2 Clearance .....	6-15
<b>4.5 Routing – Wires and Wire Bundles</b> .....	4-28	6.2.3 Insulation .....	6-17
4.5.1 Wire Crossover .....	4-28	6.2.3.1 Placement .....	6-17
4.5.2 Bend Radius .....	4-29	6.2.3.2 Damage .....	6-19
4.5.3 Coaxial Cable .....	4-30	<b>6.3 Conductor</b> .....	6-20
4.5.4 Unused Wire Termination .....	4-31	6.3.1 Deformation .....	6-20
4.5.5 Ties over Splices and Ferrules .....	4-32	6.3.2 Damage .....	6-21
<b>5 Soldering</b> .....	5-1	6.3.2.1 Stranded Wire .....	6-21
<b>5.1 Soldering Acceptability Requirements</b> .....	5-3	6.3.2.2 Solid Wire .....	6-22
<b>5.2 Soldering Anomalies</b> .....	5-4	6.3.3 Strand Separation (Birdcaging) – Presolder .....	6-22
5.2.1 Exposed Basis Metal .....	5-4	6.3.4 Strand Separation (Birdcaging) – Post-Solder .....	6-23
5.2.2 Pin Holes/Blow Holes .....	5-6	6.3.5 Tinning .....	6-24
5.2.3 Reflow of Solder Paste .....	5-7	<b>6.4 Service Loops</b> .....	6-26
5.2.4 Nonwetting .....	5-8	<b>6.5 Stress Relief</b> .....	6-27
5.2.5 Cold/Rosin Connection .....	5-9	6.5.1 Bundle .....	6-27
5.2.6 Dewetting .....	5-9	6.5.2 Lead/Wire Bend .....	6-28
5.2.7 Excess Solder .....	5-10	<b>6.6 Lead/Wire Placement – General Requirements</b> .....	6-30
5.2.7.1 Solder Balls .....	5-11	<b>6.7 Solder – General Requirements</b> .....	6-31
5.2.7.2 Bridging .....	5-12	<b>6.8 Turrets and Straight Pins</b> .....	6-33
5.2.7.3 Solder Webbing/Splashes .....	5-13	6.8.1 Lead/Wire Placement .....	6-33
5.2.8 Disturbed Solder .....	5-14	6.8.2 Solder .....	6-35
5.2.9 Fractured Solder .....	5-15	<b>6.9 Bifurcated</b> .....	6-36
5.2.10 Solder Projections .....	5-16	6.9.1 Lead/Wire Placement – Side Route Attachments .....	6-36
5.2.11 Lead-Free Fillet Lift .....	5-17	6.9.2 Lead/Wire Placement – Staked Wires .....	6-39
5.2.12 Lead-Free Hot Tear/Shrink Hole .....	5-18	6.9.3 Lead/Wire Placement – Bottom and Top Route Attachments .....	6-40
5.2.13 Probe Marks and Other Similar Surface Conditions in Solder Joints .....	5-19	6.9.4 Solder .....	6-41
5.2.14 Partially Visible or Hidden Solder Connections .....	5-20	<b>6.10 Slotted</b> .....	6-44
<b>6 Terminal Connections</b> .....	6-1	6.10.1 Lead/Wire Placement .....	6-44
<b>6.1 Swaged Hardware</b> .....	6-3	6.10.2 Solder .....	6-45
6.1.1 Terminals .....	6-3		
6.1.1.1 Terminal Base to Land Separation .....	6-3		
6.1.1.2 Turret .....	6-5		
6.1.1.3 Bifurcated .....	6-6		

## Table of Contents (cont.)

<b>5 Soldering</b> .....	5-1	6.3.3 Strand Separation (Birdcaging) – Presolder .....	6-22
<b>5.1 Soldering Acceptability Requirements</b> .....	5-3	6.3.4 Strand Separation (Birdcaging) – Post-Solder .....	6-23
<b>5.2 Soldering Anomalies</b> .....	5-4	6.3.5 Tinning .....	6-24
5.2.1 Exposed Basis Metal .....	5-4	<b>6.4 Service Loops</b> .....	6-26
5.2.2 Pin Holes/Blow Holes/Voids .....	5-6	<b>6.5 Routing – Wires and Wire Bundles – Bend Radius</b> .....	6-27
5.2.3 Reflow of Solder Paste .....	5-7	<b>6.6 Stress Relief</b> .....	6-28
5.2.4 Nonwetting .....	5-8	6.6.1 Wire .....	6-28
5.2.5 Cold/Rosin Connection .....	5-9	<b>6.7 Lead/Wire Placement – General Requirements</b> .....	6-30
5.2.6 Dewetting .....	5-9	<b>6.8 Solder – General Requirements</b> .....	6-31
5.2.7 Excess Solder .....	5-10	<b>6.9 Turrets and Straight Pins</b> .....	6-33
5.2.7.1 Solder Balls .....	5-11	6.9.1 Lead/Wire Placement .....	6-33
5.2.7.2 Bridging .....	5-12	6.9.2 Solder .....	6-35
5.2.7.3 Solder Webbing/Splashes .....	5-13	<b>6.10 Bifurcated</b> .....	6-36
5.2.8 Disturbed Solder .....	5-14	6.10.1 Lead/Wire Placement – Side Route Attachments .....	6-36
5.2.9 Cooling Lines and Secondary Reflow .....	5-15	6.10.2 Lead/Wire Placement – Staked Wires .....	6-38
5.2.10 Fractured Solder .....	5-16	6.10.3 Lead/Wire Placement – Bottom and Top Route Attachments .....	6-39
5.2.11 Solder Projections .....	5-17	6.10.4 Solder .....	6-40
5.2.12 Pb-Free Fillet Lift .....	5-18	<b>6.11 Slotted</b> .....	6-42
5.2.13 Pb-Free Hot Tear/Shrink Hole .....	5-19	6.11.1 Lead/Wire Placement .....	6-42
5.2.14 Probe Marks and Other Similar Surface Conditions in Solder Joints .....	5-20	6.11.2 Solder .....	6-43
5.2.15 Partially Visible or Hidden Solder Connections .....	5-20	<b>6.12 Pierced/Perforated</b> .....	6-44
5.2.16 Heat Shrinkable Soldering Devices .....	5-21	6.12.1 Lead/Wire Placement .....	6-44
5.2.17 Inclusions .....	5-22	6.12.2 Solder .....	6-46
<b>6 Terminal Connections</b> .....	6-1	<b>6.13 Hook</b> .....	6-47
<b>6.1 Swaged Hardware</b> .....	6-3	6.13.1 Lead/Wire Placement .....	6-47
6.1.1 Terminals .....	6-3	6.13.2 Solder .....	6-49
6.1.1.1 Terminal Base to Land Separation .....	6-3	<b>6.14 Solder Cups</b> .....	6-50
6.1.1.2 Turret .....	6-5	6.14.1 Lead/Wire Placement .....	6-50
6.1.1.3 Bifurcated .....	6-6	6.14.2 Solder .....	6-51
6.1.2 Rolled Flange .....	6-7	<b>6.15 AWG 30 and Smaller Diameter Wires – Lead/Wire Placement</b> .....	6-53
6.1.3 Flared Flange .....	6-8	<b>6.16 Series Connected</b> .....	6-55
6.1.4 Controlled Split .....	6-9	<b>6.17 Edge Clip – Position</b> .....	6-56
6.1.5 Solder .....	6-10		
<b>6.2 Insulation</b> .....	6-12		
6.2.1 Damage .....	6-12		
6.2.1.1 Presolder .....	6-12		
6.2.1.2 Post-Solder .....	6-14		
6.2.2 Clearance .....	6-15		
6.2.3 Insulation Sleeving .....	6-17		
6.2.3.1 Placement .....	6-17		
6.2.3.2 Damage .....	6-19		
<b>6.3 Conductor</b> .....	6-20		
6.3.1 Deformation .....	6-20		
6.3.2 Damage .....	6-21		
6.3.2.1 Stranded Wire .....	6-21		
6.3.2.2 Solid Wire .....	6-22		

## Table of Contents (cont.)

<b>6.11 Pierced/Perforated</b> .....	6-46	<b>7.3 Supported Holes</b> .....	7-31
6.11.1 Lead/Wire Placement .....	6-46	7.3.1 Axial Leaded – Horizontal .....	7-31
6.11.2 Solder .....	6-48	7.3.2 Axial Leaded – Vertical .....	7-33
<b>6.12 Hook</b> .....	6-49	7.3.3 Wire/Lead Protrusion .....	7-35
6.12.1 Lead/Wire Placement .....	6-49	7.3.4 Wire/Lead Clinches .....	7-36
6.12.2 Solder .....	6-51	7.3.5 Solder .....	7-38
<b>6.13 Solder Cups</b> .....	6-52	7.3.5.1 Vertical Fill (A) .....	7-41
6.13.1 Lead/Wire Placement .....	6-52	7.3.5.2 Solder Destination Side – Lead to Barrel (B) .....	7-43
6.13.2 Solder .....	6-54	7.3.5.3 Solder Destination Side – Land Area Coverage (C) .....	7-45
<b>6.14 AWG 30 and Smaller Diameter Wires – Lead/Wire Placement</b> .....	6-56	7.3.5.4 Solder Source Side – Lead to Barrel (D) .....	7-46
<b>6.15 Series Connected</b> .....	6-57	7.3.5.5 Solder Source Side – Land Area Coverage (E) .....	7-47
<b>6.16 Edge Clip – Position</b> .....	6-58	7.3.5.6 Solder Conditions – Solder in Lead Bend .....	7-48
<b>7 Through-Hole Technology</b> .....	7-1	7.3.5.7 Solder Conditions – Touching Through-Hole Component Body .....	7-49
<b>7.1 Component Mounting</b> .....	7-2	7.3.5.8 Solder Conditions – Meniscus in Solder .....	7-50
7.1.1 Orientation .....	7-2	7.3.5.9 Lead Cutting after Soldering .....	7-52
7.1.1.1 Orientation – Horizontal .....	7-3	7.3.5.10 Coated Wire Insulation in Solder .....	7-53
7.1.1.2 Orientation – Vertical .....	7-5	7.3.5.11 Interfacial Connection without Lead – Vias .....	7-54
7.1.2 Lead Forming .....	7-6	7.3.5.12 Board in Board .....	7-55
7.1.2.1 Bend Radius .....	7-6	<b>7.4 Unsupported Holes</b> .....	7-58
7.1.2.2 Space between Seal/Weld and Bend .....	7-7	7.4.1 Axial Leads – Horizontal .....	7-58
7.1.2.3 Stress Relief .....	7-8	7.4.2 Axial Leads – Vertical .....	7-59
7.1.2.4 Damage .....	7-10	7.4.3 Wire/Lead Protrusion .....	7-60
7.1.3 Leads Crossing Conductors .....	7-11	7.4.4 Wire/Lead Clinches .....	7-61
7.1.4 Hole Obstruction .....	7-12	7.4.5 Solder .....	7-63
7.1.5 DIP/SIP Devices and Sockets .....	7-13	7.4.6 Lead Cutting after Soldering .....	7-65
7.1.6 Radial Leads – Vertical .....	7-15	<b>7.5 Jumper Wires</b> .....	7-66
7.1.6.1 Spacers .....	7-16	7.5.1 Wire Selection .....	7-66
7.1.7 Radial Leads – Horizontal .....	7-18	7.5.2 Wire Routing .....	7-67
7.1.8 Connectors .....	7-19	7.5.3 Wire Staking .....	7-69
7.1.8.1 Right Angle .....	7-21	7.5.4 Supported Holes .....	7-71
7.1.8.2 Vertical Shrouded Pin Headers and Vertical Receptacle Connectors .....	7-22	7.5.4.1 Supported Holes – Lead in Hole .....	7-71
7.1.9 Conductive Cases .....	7-23	7.5.5 Wrapped Attachment .....	7-72
<b>7.2 Component Securing</b> .....	7-23	7.5.6 Lap Soldered .....	7-73
7.2.1 Mounting Clips .....	7-23	<b>8 Surface Mount Assemblies</b> .....	8-1
7.2.2 Adhesive Bonding .....	7-25	<b>8.1 Staking Adhesive</b> .....	8-3
7.2.2.1 Adhesive Bonding – Nonelevated Components .....	7-26	8.1.1 Component Bonding .....	8-3
7.2.2.2 Adhesive Bonding – Elevated Components .....	7-29	8.1.2 Mechanical Strength .....	8-4
7.2.3 Other Devices .....	7-30	<b>8.2 SMT Leads</b> .....	8-6
		8.2.1 Plastic Components .....	8-6
		8.2.2 Damage .....	8-6
		8.2.3 Flattening .....	8-7

## Table of Contents (cont.)

<b>7 Through-Hole Technology</b> .....	7-1	<b>7.4 Unsupported Holes</b> .....	7-56
<b>7.1 Component Mounting</b> .....	7-2	7.4.1 Axial Leads – Horizontal .....	7-56
7.1.1 Orientation .....	7-2	7.4.2 Axial Leads – Vertical .....	7-57
7.1.1.1 Orientation – Horizontal .....	7-3	7.4.3 Wire/Lead Protrusion .....	7-58
7.1.1.2 Orientation – Vertical .....	7-4	7.4.4 Wire/Lead Clinches .....	7-59
7.1.2 Lead Forming .....	7-5	7.4.5 Solder .....	7-61
7.1.2.1 Bend Radius .....	7-5	7.4.6 Lead Cutting after Soldering .....	7-63
7.1.2.2 Space between Seal/Weld and Bend .....	7-6		
7.1.2.3 Stress Relief .....	7-7	<b>8 Surface Mount Assemblies</b> .....	8-1
7.1.2.4 Damage .....	7-9	<b>8.1 Staking Adhesive</b> .....	8-3
7.1.3 Leads Crossing Conductors .....	7-10	8.1.1 Component Bonding .....	8-3
7.1.4 Hole Obstruction .....	7-11	8.1.2 Mechanical Strength .....	8-4
7.1.5 DIP/SIP Devices and Sockets .....	7-12		
7.1.6 Radial Leads – Vertical .....	7-14	<b>8.2 SMT Leads</b> .....	8-6
7.1.6.1 Spacers .....	7-15	8.2.1 Plastic Components .....	8-6
7.1.7 Radial Leads – Horizontal .....	7-16	8.2.2 Damage .....	8-6
7.1.8 Connectors .....	7-17	8.2.3 Flattening .....	8-7
7.1.8.1 Right Angle .....	7-18		
7.1.8.2 Vertical Shrouded Pin Headers and Vertical Receptacle Connectors .....	7-19	<b>8.3 SMT Connections</b> .....	8-7
7.1.9 Conductive Cases .....	7-20	<b>8.3.1 Chip Components – Bottom Only</b> <b>Terminations</b> .....	8-8
<b>7.2 Component Securing</b> .....	7-20	8.3.1.1 Side Overhang (A) .....	8-9
7.2.1 Mounting Clips .....	7-20	8.3.1.2 End Overhang (B) .....	8-10
7.2.2 Adhesive Bonding .....	7-22	8.3.1.3 End Joint Width (C) .....	8-11
7.2.2.1 Adhesive Bonding – Nonelevated Components .....	7-23	8.3.1.4 Side Joint Length (D) .....	8-12
7.2.2.2 Adhesive Bonding – Elevated Components .....	7-26	8.3.1.5 Maximum Fillet Height (E) .....	8-13
7.2.3 Other Devices .....	7-29	8.3.1.6 Minimum Fillet Height (F) .....	8-13
		8.3.1.7 Solder Thickness (G) .....	8-14
		8.3.1.8 End Overlap (J) .....	8-14
<b>7.3 Supported Holes</b> .....	7-30	<b>8.3.2 Rectangular or Square End Chip</b> <b>Components – 1, 2, 3 or 5 Side</b> <b>Termination(s)</b> .....	8-15
7.3.1 Axial Leaded – Horizontal .....	7-30	8.3.2.1 Side Overhang (A) .....	8-16
7.3.2 Axial Leaded – Vertical .....	7-31	8.3.2.2 End Overhang (B) .....	8-18
7.3.3 Wire/Lead Protrusion .....	7-33	8.3.2.3 End Joint Width (C) .....	8-19
7.3.4 Wire/Lead Clinches .....	7-34	8.3.2.4 Side Joint Length (D) .....	8-21
7.3.5 Solder .....	7-36	8.3.2.5 Maximum Fillet Height (E) .....	8-22
7.3.5.1 Vertical Fill (A) .....	7-39	8.3.2.6 Minimum Fillet Height (F) .....	8-23
7.3.5.2 Solder Destination Side – Lead to Barrel (B) .....	7-41	8.3.2.7 Solder Thickness (G) .....	8-24
7.3.5.3 Solder Destination Side – Land Area Coverage (C) .....	7-43	8.3.2.8 End Overlap (J) .....	8-25
7.3.5.4 Solder Source Side – Lead to Barrel (D) .....	7-44	8.3.2.9 Termination Variations .....	8-26
7.3.5.5 Solder Source Side – Land Area Coverage (E) .....	7-45	8.3.2.9.1 Mounting on Side (Billboarding) .....	8-26
7.3.5.6 Solder Conditions – Solder in Lead Bend .....	7-46	8.3.2.9.2 Mounting Upside Down .....	8-28
7.3.5.7 Solder Conditions – Touching Through-Hole Component Body .....	7-47	8.3.2.9.3 Stacking .....	8-29
7.3.5.8 Solder Conditions – Meniscus in Solder .....	7-48	8.3.2.9.4 Tombstoning .....	8-30
7.3.5.9 Lead Cutting after Soldering .....	7-50	8.3.2.10 Center Terminations .....	8-31
7.3.5.10 Coated Wire Insulation in Solder .....	7-51	8.3.2.10.1 Solder Width of Side Termination .....	8-31
7.3.5.11 Interfacial Connection without Lead – Vias .....	7-52	8.3.2.10.2 Minimum Fillet Height of Side Termination ...	8-32
7.3.5.12 Board in Board .....	7-53		

## Table of Contents (cont.)

<b>8.3 SMT Connections</b> .....	8-7	8.3.4.6 Minimum Fillet Height (F) .....	8-46
<b>8.3.1 Chip Components – Bottom Only</b>		8.3.4.7 Solder Thickness (G) .....	8-46
<b>Terminations</b> .....	8-8	<b>8.3.5 Flat Gull Wing Leads</b> .....	8-47
8.3.1.1 Side Overhang (A) .....	8-9	8.3.5.1 Side Overhang (A) .....	8-47
8.3.1.2 End Overhang (B) .....	8-10	8.3.5.2 Toe Overhang (B) .....	8-51
8.3.1.3 End Joint Width (C) .....	8-11	8.3.5.3 Minimum End Joint Width (C) .....	8-52
8.3.1.4 Side Joint Length (D) .....	8-12	8.3.5.4 Minimum Side Joint Length (D) .....	8-54
8.3.1.5 Maximum Fillet Height (E) .....	8-13	8.3.5.5 Maximum Heel Fillet Height (E) .....	8-56
8.3.1.6 Minimum Fillet Height (F) .....	8-13	8.3.5.6 Minimum Heel Fillet Height (F) .....	8-57
8.3.1.7 Solder Thickness (G) .....	8-14	8.3.5.7 Solder Thickness (G) .....	8-58
8.3.1.8 End Overlap (J) .....	8-14	8.3.5.8 Coplanarity .....	8-59
<b>8.3.2 Rectangular or Square End Chip</b>		<b>8.3.6 Round or Flattened (Coined) Gull</b>	
<b>Components – 1, 2, 3 or 5 Side</b>		<b>Wing Leads</b> .....	8-60
<b>Termination(s)</b> .....	8-15	8.3.6.1 Side Overhang (A) .....	8-61
8.3.2.1 Side Overhang (A) .....	8-16	8.3.6.2 Toe Overhang (B) .....	8-62
8.3.2.2 End Overhang (B) .....	8-18	8.3.6.3 Minimum End Joint Width (C) .....	8-62
8.3.2.3 End Joint Width (C) .....	8-19	8.3.6.4 Minimum Side Joint Length (D) .....	8-63
8.3.2.4 Side Joint Length (D) .....	8-21	8.3.6.5 Maximum Heel Fillet Height (E) .....	8-64
8.3.2.5 Maximum Fillet Height (E) .....	8-22	8.3.6.6 Minimum Heel Fillet Height (F) .....	8-65
8.3.2.6 Minimum Fillet Height (F) .....	8-23	8.3.6.7 Solder Thickness (G) .....	8-66
8.3.2.7 Solder Thickness (G) .....	8-24	8.3.6.8 Minimum Side Joint Height (Q) .....	8-66
8.3.2.8 End Overlap (J) .....	8-25	8.3.6.9 Coplanarity .....	8-67
8.3.2.9 Termination Variations .....	8-26	<b>8.3.7 J Leads</b> .....	8-68
8.3.2.9.1 Mounting on Side (Billboarding) .....	8-26	8.3.7.1 Side Overhang (A) .....	8-68
8.3.2.9.2 Mounting Upside Down .....	8-28	8.3.7.2 Toe Overhang (B) .....	8-70
8.3.2.9.3 Stacking .....	8-29	8.3.7.3 End Joint Width (C) .....	8-70
8.3.2.9.4 Tombstoning .....	8-30	8.3.7.4 Side Joint Length (D) .....	8-72
8.3.2.10 Center Terminations .....	8-31	8.3.7.5 Maximum Heel Fillet Height (E) .....	8-73
8.3.2.10.1 Solder Width of Side Termination .....	8-31	8.3.7.6 Minimum Heel Fillet Height (F) .....	8-74
8.3.2.10.2 Minimum Fillet Height of Side Termination ...	8-32	8.3.7.7 Solder Thickness (G) .....	8-76
<b>8.3.3 Cylindrical End Cap Terminations</b> .....	8-33	8.3.7.8 Coplanarity .....	8-76
8.3.3.1 Side Overhang (A) .....	8-34	<b>8.3.8 Butt/I Connections</b> .....	8-77
8.3.3.2 End Overhang (B) .....	8-35	8.3.8.1 Modified Through-Hole Terminations .....	8-77
8.3.3.3 End Joint Width (C) .....	8-36	8.3.8.1.1 Maximum Side Overhang (A) .....	8-78
8.3.3.4 Side Joint Length (D) .....	8-37	8.3.8.1.2 Toe Overhang (B) .....	8-78
8.3.3.5 Maximum Fillet Height (E) .....	8-38	8.3.8.1.3 Minimum End Joint Width (C) .....	8-79
8.3.3.6 Minimum Fillet Height (F) .....	8-39	8.3.8.1.4 Minimum Side Joint Length (D) .....	8-79
8.3.3.7 Solder Thickness (G) .....	8-40	8.3.8.1.5 Maximum Fillet Height (E) .....	8-79
8.3.3.8 End Overlap (J) .....	8-41	8.3.8.1.6 Minimum Fillet Height (F) .....	8-80
<b>8.3.4 Castellated Terminations</b> .....	8-42	8.3.8.1.7 Solder Thickness (G) .....	8-80
8.3.4.1 Side Overhang (A) .....	8-43	8.3.8.2 Solder Charged Terminations .....	8-81
8.3.4.2 End Overhang (B) .....	8-44	8.3.8.2.1 Maximum Side Overhang (A) .....	8-82
8.3.4.3 Minimum End Joint Width (C) .....	8-44	8.3.8.2.2 Maximum Toe Overhang (B) .....	8-82
8.3.4.4 Minimum Side Joint Length (D) .....	8-45	8.3.8.2.3 Minimum End Joint Width (C) .....	8-83
8.3.4.5 Maximum Fillet Height (E) .....	8-45	8.3.8.2.4 Minimum Fillet Height (F) .....	8-83

## Table of Contents (cont.)

<b>8.3.3 Cylindrical End Cap Terminations</b> .....	8-33	<b>8.3.8 Butt/I Connections</b> .....	8-75
8.3.3.1 Side Overhang (A) .....	8-34	8.3.8.1 Modified Through-Hole Terminations .....	8-75
8.3.3.2 End Overhang (B) .....	8-35	8.3.8.1.1 Maximum Side Overhang (A) .....	8-76
8.3.3.3 End Joint Width (C) .....	8-36	8.3.8.1.2 Toe Overhang (B) .....	8-76
8.3.3.4 Side Joint Length (D) .....	8-37	8.3.8.1.3 Minimum End Joint Width (C) .....	8-77
8.3.3.5 Maximum Fillet Height (E) .....	8-38	8.3.8.1.4 Minimum Side Joint Length (D) .....	8-77
8.3.3.6 Minimum Fillet Height (F) .....	8-39	8.3.8.1.5 Maximum Fillet Height (E) .....	8-77
8.3.3.7 Solder Thickness (G) .....	8-40	8.3.8.1.6 Minimum Fillet Height (F) .....	8-78
8.3.3.8 End Overlap (J) .....	8-41	8.3.8.1.7 Solder Thickness (G) .....	8-78
<b>8.3.4 Castellated Terminations</b> .....	8-42	8.3.8.2 Solder Charged Terminations .....	8-79
8.3.4.1 Side Overhang (A) .....	8-43	8.3.8.2.1 Maximum Side Overhang (A) .....	8-80
8.3.4.2 End Overhang (B) .....	8-44	8.3.8.2.2 Maximum Toe Overhang (B) .....	8-80
8.3.4.3 Minimum End Joint Width (C) .....	8-44	8.3.8.2.3 Minimum End Joint Width (C) .....	8-81
8.3.4.4 Minimum Side Joint Length (D) .....	8-45	8.3.8.2.4 Minimum Fillet Height (F) .....	8-81
8.3.4.5 Maximum Fillet Height (E) .....	8-45	<b>8.3.9 Flat Lug Leads</b> .....	8-82
8.3.4.6 Minimum Fillet Height (F) .....	8-46	<b>8.3.10 Tall Profile Components Having Bottom Only Terminations</b> .....	8-83
8.3.4.7 Solder Thickness (G) .....	8-46	<b>8.3.11 Inward Formed L-Shaped Ribbon Leads</b> .....	8-84
<b>8.3.5 Flat Gull Wing Leads</b> .....	8-47	<b>8.3.12 Surface Mount Area Array</b> .....	8-86
8.3.5.1 Side Overhang (A) .....	8-48	8.3.12.1 Alignment .....	8-87
8.3.5.2 Toe Overhang (B) .....	8-51	8.3.12.2 Solder Ball Spacing .....	8-87
8.3.5.3 Minimum End Joint Width (C) .....	8-52	8.3.12.3 Solder Connections .....	8-88
8.3.5.4 Minimum Side Joint Length (D) .....	8-53	8.3.12.4 Voids .....	8-90
8.3.5.5 Maximum Heel Fillet Height (E) .....	8-54	8.3.12.5 Underfill/Staking .....	8-90
8.3.5.6 Minimum Heel Fillet Height (F) .....	8-55	8.3.12.6 Package on Package .....	8-91
8.3.5.7 Solder Thickness (G) .....	8-56	<b>8.3.13 Bottom Termination Components (BTC)</b> .....	8-93
8.3.5.8 Coplanarity .....	8-57	<b>8.3.14 Components with Bottom Thermal Plane Terminations (D-Pak)</b> .....	8-95
<b>8.3.6 Round or Flattened (Coined) Gull Wing Leads</b> .....	8-58	<b>8.3.15 Flattened Post Connections</b> .....	8-97
8.3.6.1 Side Overhang (A) .....	8-59	8.3.15.1 Maximum Termination Overhang – Square Solder Land .....	8-97
8.3.6.2 Toe Overhang (B) .....	8-60	8.3.15.2 Maximum Termination Overhang – Round Solder Land .....	8-98
8.3.6.3 Minimum End Joint Width (C) .....	8-60	8.3.15.3 Maximum Fillet Height .....	8-98
8.3.6.4 Minimum Side Joint Length (D) .....	8-61	<b>8.3.16 P-Style Terminations</b> .....	8-99
8.3.6.5 Maximum Heel Fillet Height (E) .....	8-62	8.3.16.1 Maximum Side Overhang (A) .....	8-100
8.3.6.6 Minimum Heel Fillet Height (F) .....	8-63	8.3.16.2 Maximum Toe Overhang (B) .....	8-100
8.3.6.7 Solder Thickness (G) .....	8-64	8.3.16.3 Minimum End Joint Width (C) .....	8-101
8.3.6.8 Minimum Side Joint Height (Q) .....	8-64	8.3.16.4 Minimum Side Joint Length (D) .....	8-101
8.3.6.9 Coplanarity .....	8-65	8.3.16.5 Minimum Fillet Height (F) .....	8-102
<b>8.3.7 J Leads</b> .....	8-66	<b>8.3.17 Vertical Cylindrical Cans with Outward L-Shaped Lead Terminations</b> .....	8-103
8.3.7.1 Side Overhang (A) .....	8-66		
8.3.7.2 Toe Overhang (B) .....	8-68		
8.3.7.3 End Joint Width (C) .....	8-69		
8.3.7.4 Side Joint Length (D) .....	8-70		
8.3.7.5 Maximum Heel Fillet Height (E) .....	8-71		
8.3.7.6 Minimum Heel Fillet Height (F) .....	8-72		
8.3.7.7 Solder Thickness (G) .....	8-74		
8.3.7.8 Coplanarity .....	8-74		



## Table of Contents (cont.)

<b>8.3.9 Flat Lug Leads and Flat Unformed Leads</b> .....	8-84	<b>9.2 Chip Resistor Element</b> .....	9-3
<b>8.3.10 Tall Profile Components Having Bottom Only Terminations</b> .....	8-86	<b>9.3 Leaded/Leadless Devices</b> .....	9-4
<b>8.3.11 Inward Formed L-Shaped Ribbon Leads</b> .....	8-87	<b>9.4 Ceramic Chip Capacitors</b> .....	9-8
<b>8.3.12 Surface Mount Area Array</b> .....	8-89	<b>9.5 Connectors</b> .....	9-10
8.3.12.1 Alignment .....	8-90	<b>9.6 Relays</b> .....	9-13
8.3.12.2 Solder Ball Spacing .....	8-90	<b>9.7 Magnetic Components</b> .....	9-13
8.3.12.3 Solder Connections .....	8-91	<b>9.8 Connectors, Handles, Extractors, Latches</b> .....	9-14
8.3.12.4 Voids .....	8-93	<b>9.9 Edge Connector Pins</b> .....	9-15
8.3.12.5 Underfill/Staking .....	8-93	<b>9.10 Press Fit Pins</b> .....	9-16
8.3.12.6 Package on Package .....	8-94	<b>9.11 Backplane Connector Pins</b> .....	9-17
<b>8.3.13 Bottom Termination Components (BTC)</b> .....	8-96	<b>9.12 Heat Sink Hardware</b> .....	9-18
<b>8.3.14 Components with Bottom Thermal Plane Terminations</b> .....	8-98	<b>9.13 Threaded Items and Hardware</b> .....	9-19
<b>8.3.15 Flattened Post Connections</b> .....	8-100	<b>10 Printed Circuit Boards and Assemblies</b> .....	10-1
8.3.15.1 Maximum Termination Overhang – Square Solder Land .....	8-100	<b>10.1 Non-Soldered Contact Areas</b> .....	10-2
8.3.15.2 Maximum Termination Overhang – Round Solder Land .....	8-101	10.1.1 Contamination .....	10-2
8.3.15.3 Maximum Fillet Height .....	8-101	10.1.2 Damage .....	10-4
<b>8.3.16 P-Style Connections</b> .....	8-102	<b>10.2 Laminate Conditions</b> .....	10-4
8.3.16.1 Maximum Side Overhang (A) .....	8-103	10.2.1 Measling and Cracking .....	10-5
8.3.16.2 Maximum Toe Overhang (B) .....	8-103	10.2.2 Blistering and Delamination .....	10-7
8.3.16.3 Minimum End Joint Width (C) .....	8-104	10.2.3 Weave Texture/Weave Exposure .....	10-9
8.3.16.4 Minimum Side Joint Length (D) .....	8-104	10.2.4 Haloing .....	10-10
8.3.16.5 Minimum Fillet Height (F) .....	8-105	10.2.5 Edge Delamination, Nicks and Cracking .....	10-12
<b>8.4 Specialized SMT Terminations</b> .....	8-106	10.2.6 Burns .....	10-14
<b>8.5 Surface Mount Connectors</b> .....	8-107	10.2.7 Bow and Twist .....	10-15
<b>8.6 Jumper Wires</b> .....	8-108	10.2.8 Depanelization .....	10-16
8.6.1 SMT .....	8-109	<b>10.3 Conductors/Lands</b> .....	10-18
8.6.1.1 Chip and Cylindrical End Cap Components .....	8-109	10.3.1 Reduction .....	10-18
8.6.1.2 Gull Wing .....	8-110	10.3.2 Lifted .....	10-19
8.6.1.3 J Lead .....	8-111	10.3.3 Mechanical Damage .....	10-21
8.6.1.4 Castellations .....	8-111	<b>10.4 Flexible and Rigid-Flex Printed Circuitry</b> .....	10-22
8.6.1.5 Land .....	8-112	10.4.1 Damage .....	10-22
<b>9 Component Damage</b> .....	9-1	10.4.2 Delamination/Blister .....	10-24
<b>9.1 Loss of Metallization</b> .....	9-2	10.4.2.1 Flex .....	10-24
		10.4.2.2 Flex to Stiffener .....	10-25
		10.4.3 Solder Wicking .....	10-26
		10.4.4 Attachment .....	10-27

## Table of Contents (cont.)

<b>8.3.18 Flexible and Rigid Flex Printed Circuitry with Flat Unformed Leads</b> .....	8-105	10.2.4 Haloing .....	10-10
<b>8.3.19 Wrapped Terminals</b> .....	8-106	10.2.5 Edge Delamination, Nicks and Cracking .....	10-12
8.3.19.1 Side Overhang (A) .....	8-107	10.2.6 Burns .....	10-14
8.3.19.2 End Joint Width (C) .....	8-107	10.2.7 Bow and Twist .....	10-15
8.3.19.3 Side Joint Length (D) .....	8-107	10.2.8 Depanelization .....	10-16
8.3.19.4 Maximum Heel Fillet Height (E) .....	8-107	<b>10.3 Conductors/Lands</b> .....	10-18
8.3.19.5 Minimum Heel Fillet Height (F) .....	8-108	10.3.1 Reduction .....	10-18
8.3.19.6 Solder Thickness (G) .....	8-108	10.3.2 Lifted .....	10-19
<b>8.4 Specialized SMT Terminations</b> .....	8-109	10.3.3 Mechanical Damage .....	10-21
<b>8.5 Surface Mount Connectors</b> .....	8-110	<b>10.4 Flexible and Rigid-Flex Printed Boards</b> .....	10-22
8.5.1 Surface Mount Threaded Standoffs (SMTs) or Surface Mount Fasteners .....	8-111	10.4.1 Damage .....	10-22
<b>9 Component Damage</b> .....	9-1	10.4.2 Delamination/Blister .....	10-24
<b>9.1 Loss of Metallization</b> .....	9-2	10.4.2.1 Flex .....	10-24
<b>9.2 Chip Resistor Element</b> .....	9-3	10.4.2.2 Flex to Stiffener .....	10-25
<b>9.3 Leaded/Leadless Devices</b> .....	9-4	10.4.3 Solder Wicking .....	10-26
<b>9.4 Ceramic Chip Capacitors</b> .....	9-8	10.4.4 Attachment .....	10-27
<b>9.5 Connectors</b> .....	9-10	<b>10.5 Marking</b> .....	10-28
<b>9.6 Relays</b> .....	9-13	10.5.1 Etched (Including Hand Printing) .....	10-30
<b>9.7 Ferrite Core Components</b> .....	9-13	10.5.2 Screened .....	10-31
<b>9.8 Connectors, Handles, Extractors, Latches</b> .....	9-14	10.5.3 Stamped .....	10-32
<b>9.9 Edge Connector Pins</b> .....	9-15	10.5.4 Laser .....	10-33
<b>9.10 Press Fit Pins</b> .....	9-16	10.5.5 Labels .....	10-33
<b>9.11 Backplane Connector Pins</b> .....	9-17	10.5.5.1 Bar Coding/Data Matrix .....	10-33
<b>9.12 Heat Sink Hardware</b> .....	9-18	10.5.5.2 Readability .....	10-34
<b>9.13 Threaded Items and Hardware</b> .....	9-19	10.5.5.3 Labels – Adhesion and Damage .....	10-35
<b>10 Printed Boards and Assemblies</b> .....	10-1	10.5.5.4 Position .....	10-35
<b>10.1 Non-Soldered Contact Areas</b> .....	10-2	10.5.6 Radio Frequency Identification (RFID) Tags .....	10-36
10.1.1 Contamination .....	10-2	<b>10.6 Cleanliness</b> .....	10-37
10.1.2 Damage .....	10-4	10.6.1 Flux Residues .....	10-37
<b>10.2 Laminate Conditions</b> .....	10-4	10.6.1.1 Cleaning Required .....	10-38
10.2.1 Measling and Cracking .....	10-5	10.6.1.2 No Cleaning Process .....	10-39
10.2.2 Blistering and Delamination .....	10-7	10.6.2 Foreign Object Debris (FOD) .....	10-40
10.2.3 Weave Texture/Weave Exposure .....	10-9	10.6.3 Chlorides, Carbonates and White Residues .....	10-41
		10.6.4 Surface Appearance .....	10-43
		<b>10.7 Solder Mask Coating</b> .....	10-44
		10.7.1 Wrinkling/Cracking .....	10-45
		10.7.2 Voids, Blisters, Scratches .....	10-47
		10.7.3 Breakdown .....	10-48
		10.7.4 Discoloration .....	10-49
		<b>10.8 Conformal Coating</b> .....	10-49
		10.8.1 General .....	10-49
		10.8.2 Coverage .....	10-50
		10.8.3 Thickness .....	10-52
		<b>10.9 Electrical Insulation Coating</b> .....	10-53
		10.9.1 Coverage .....	10-53
		10.9.2 Thickness .....	10-53

## Table of Contents (cont.)

<b>10.5 Marking</b> .....	10-28	10.8.2 Coverage .....	10-52
10.5.1 Etched (Including Hand Printing) .....	10-30	10.8.3 Thickness .....	10-54
10.5.2 Screened .....	10-31	10.8.4 Electrical Insulation Coating .....	10-55
10.5.3 Stamped .....	10-33	10.8.4.1 Coverage .....	10-55
10.5.4 Laser .....	10-34	10.8.4.2 Thickness .....	10-55
10.5.5 Labels .....	10-35		
10.5.5.1 Bar Coding/Data Matrix .....	10-35	<b>10.9 Encapsulation</b> .....	10-56
10.5.5.2 Readability .....	10-36		
10.5.5.3 Labels – Adhesion and Damage .....	10-37	<b>11 Discrete Wiring</b> .....	11-1
10.5.5.4 Position .....	10-37		
10.5.6 Radio Frequency Identification (RFID) Tags .....	10-38	<b>11.1 Solderless Wrap</b> .....	11-2
		11.1.1 Number of Turns .....	11-3
<b>10.6 Cleanliness</b> .....	10-39	11.1.2 Turn Spacing .....	11-4
10.6.1 Flux Residues .....	10-40	11.1.3 End Tails and Insulation Wrap .....	11-5
10.6.2 Foreign Object Debris (FOD) .....	10-41	11.1.4 Raised Turns Overlap .....	11-7
10.6.3 Chlorides, Carbonates and White Residues .....	10-42	11.1.5 Connection Position .....	11-8
10.6.4 Flux Residues – No-Clean Process – Appearance .....	10-44	11.1.6 Wire Dress .....	11-10
10.6.5 Surface Appearance .....	10-45	11.1.7 Wire Slack .....	11-11
		11.1.8 Wire Plating .....	11-12
<b>10.7 Solder Mask Coating</b> .....	10-46	11.1.9 Damaged Insulation .....	11-13
10.7.1 Wrinkling/Cracking .....	10-47	11.1.10 Damaged Conductors and Terminals .....	11-14
10.7.2 Voids, Blisters, Scratches .....	10-49		
10.7.3 Breakdown .....	10-50	<b>12 High Voltage</b> .....	12-1
10.7.4 Discoloration .....	10-51		
		<b>Appendix A Minimum Electrical Clearance – Electrical Conductor Spacing</b> .....	A-1
<b>10.8 Conformal Coating</b> .....	10-51		
10.8.1 General .....	10-51	<b>Index</b> .....	Index-1

## Table of Contents (cont.)

<b>10.10 Encapsulation</b> .....	10-54	<b>Table 6-6 Staking Requirements of Side Route Straight Through Connections – Bifurcated Terminals</b> .....	6-38
<b>11 Discrete Wiring</b> .....	11-1	<b>Table 6-7 Bifurcated Terminal Lead/Wire Placement – Bottom Route</b> .....	6-39
<b>11.1 Solderless Wrap</b> .....	11-1	<b>Table 6-8 Pierced or Perforated Terminal Lead/Wire Placement</b> .....	6-44
<b>12 High Voltage</b> .....	12-1	<b>Table 6-9 Hook Terminal Lead/Wire Placement</b> .....	6-47
<b>13 Jumper Wires</b> .....	13-1	<b>Table 6-10 AWG 30 and Smaller Wire Wrap Requirements</b> .....	6-53
<b>13.1 Wire Routing</b> .....	13-2	<b>Table 7-1 Lead Bend Radius</b> .....	7-5
<b>13.2 Wire Staking – Adhesive or Tape</b> .....	13-3	<b>Table 7-2 Component to Land Clearance</b> .....	7-31
<b>13.3 Terminations</b> .....	13-4	<b>Table 7-3 Protrusion of Wires/Leads in Supported Holes</b> .....	7-33
13.3.1 Lap .....	13-5	<b>Table 7-4 Plated Through-Holes with Component Leads – Minimum Acceptable Solder Conditions</b> .....	7-38
13.3.1.1 Component Lead .....	13-5	<b>Table 7-5 Board in Board – Minimum Acceptable Solder Conditions</b> .....	7-53
13.3.1.2 Land .....	13-7	<b>Table 7-6 Protrusion of Leads in Unsupported Holes</b> .....	7-58
13.3.2 Wire in Hole .....	13-8	<b>Table 7-7 Unsupported Holes with Component Leads, Minimum Acceptable Conditions</b> .....	7-61
13.3.3 Wrapped .....	13-9	<b>Table 8-1 Dimensional Criteria – Chip Component – Bottom Only Termination Features</b> .....	8-8
13.3.4 SMT .....	13-10	<b>Table 8-2 Dimensional Criteria – Rectangular or Square End Chip Components – 1, 2, 3 or 5 Side Termination(s)</b> .....	8-15
13.3.4.1 Chip and Cylindrical End Cap Components .....	13-10	<b>Table 8-3 Dimensional Criteria – Cylindrical End Cap Termination</b> .....	8-33
13.3.4.2 Gull Wing .....	13-11	<b>Table 8-4 Dimensional Criteria – Castellated Terminations</b> .....	8-42
13.3.4.3 Castellations .....	13-13	<b>Table 8-5 Dimensional Criteria – Flat Gull Wing Leads</b> .....	8-47
<b>Appendix A Minimum Electrical Clearance</b> .....	A-1	<b>Table 8-6 Dimensional Criteria – Round or Flattened (Coined) Gull Wire Lead Features</b> .....	8-58
<b>Appendix B Protecting the Assembly – ESD and Other Handling Considerations</b> .....	B-1		
<b>Index</b> .....	Index-1		
<b>Tables</b>			
<b>Table 1-1 Summary of Related Documents</b> .....	1-1		
<b>Table 1-2 Inspection Magnification (Land Width)</b> .....	1-7		
<b>Table 1-3 Magnification Aid Applications For Wires And Wire Connections</b> .....	1-8		
<b>Table 1-4 Magnification Aid Applications – Other</b> .....	1-8		
<b>Table 6-1 Swaged Hardware Minimum Soldering Requirements</b> .....	6-10		
<b>Table 6-2 Strand Damage</b> .....	6-21		
<b>Table 6-3 Minimum Bend Radius Requirements</b> .....	6-27		
<b>Table 6-4 Turret or Straight Pin Terminal Lead/Wire Placement</b> .....	6-33		
<b>Table 6-5 Bifurcated Terminal Lead/Wire Placement – Side Route</b> .....	6-36		



## Table of Contents (cont.)

<b>Table 8-7 Dimensional Criteria – J Leads</b> ..... 8-66	<b>Table 8-18 Dimensional Criteria Flattened Post Connections</b> ..... 8-97
<b>Table 8-8 Dimensional Criteria – Butt/Connections – Modified Through-Hole Leads</b> ..... 8-75	<b>Table 8-19 Dimensional Criteria – P-Style Terminations</b> ..... 8-99
<b>Table 8-9 Dimensional Criteria – Butt/Connections – Solder Charged Terminations</b> ..... 8-79	<b>Table 8-20 Dimensional Criteria – Vertical Cylindrical Cans with Outward L-Shaped Lead Terminations</b> ..... 8-104
<b>Table 8-10 Dimensional Criteria – Flat Lug Leads</b> ..... 8-82	<b>Table 8-21 Dimensional Criteria – Flexible and Rigid-Flex Circuitry with Flat Unformed Leads</b> ..... 8-105
<b>Table 8-11 Dimensional Criteria – Tall Profile Components Having Bottom Only Terminations</b> ..... 8-83	<b>Table 8-22 Dimensional Criteria – Wrapped Terminals</b> ..... 8-106
<b>Table 8-12 Dimensional Criteria – Inward Formed L-Shaped Ribbon Leads</b> ..... 8-84	<b>Table 8-23 SMTS/Surface Mount Fasteners – Minimum Acceptable Solder Conditions</b> ..... 8-111
<b>Table 8-13 Dimensional Criteria – Ball Grid Array Components with Collapsing Balls</b> ..... 8-86	<b>Table 9-1 Chip-Out Criteria</b> ..... 9-8
<b>Table 8-14 Ball Grid Array Components with Noncollapsing Balls</b> ..... 8-86	<b>Table 10-1 Coating Thickness</b> ..... 10-52
<b>Table 8-15 Column Grid Array</b> ..... 8-86	<b>Appendix A Table 6-1 Electrical Conductor Spacing</b> ..... A-2
<b>Table 8-16 Dimensional Criteria – BTC</b> ..... 8-93	<b>Table B-1 Typical Static Charge Sources</b> ..... B-3
<b>Table 8-17 Dimensional Criteria – Bottom Thermal Plane Terminations (D-Pak)</b> .... 8-95	<b>Table B-2 Typical Static Voltage Generation</b> ..... B-3
	<b>Table B-3 Recommended Practices for Handling Electronic Assemblies</b> ..... B-6